

# TQ-M4-VSP

- 於平滑面實施超細微處理之極低粗度電解銅箔(VSP箔)  
Very smooth profile ED copper foil (VSP) with very low profile surface treatment.
- 銅箔於全面蝕刻後, 於PI具良好的透視度。  
Very good performance for transparency and visibility of PI after etching copper foil.
- 超低粗度處理面, 非常適合於高頻高速的應用。  
Possible to use high frequency application due to very low profile.

## 用途/Application

- 軟性電路板  
/Flexible Print Board

## 構成/Composition



## 生產地點/Production Site

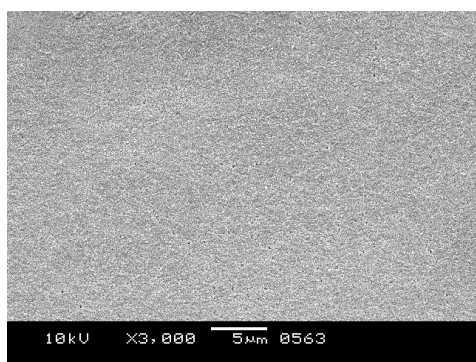
- 日本/Japan

## 代表性特性數據/Representative

	$\mu\text{m}$	Laminate side Rz( $\mu\text{m}$ )	Tensile Strength (N/mm <sup>2</sup> )	Elongation (%)	Peel Strength (kg/cm)@FR-4
TQ-M4-VSP	12	0.6	340	9	0.6

※上述表列為代表性數據非保證值  
This is representative data, not guarantee.

處理面/Laminate side



阻劑面/ resist side

